

Hairtail+ 800G NDR OSFP TO 2xQSFP112

Active Direct Attached Cable



FEATURES

- Modules compliant to OSFP MSA & QSFP112 MSA
- InfiniBand NDR compatible
- Transmission data rate up to PAM4 106.25Gbps per channel
- Low power consumption
- Linear PAM4 programmable equalizer optimized for 56GBaud copper link up to max length 5M on 25AWG
- Enable Auto-Negotiation and Link Training
- Supports device programming by MCU with I2C
- Power supply 3.3V
- Operating case temperature 0°C to +70°C
- RoHS2.0 compliant

Absolute Maximum Ratings

Parameter	Symbol	Min	Typical	Max	Unit
Supply Voltage	V _{cc}	-0.3	3.3	3.6	V
Storage temperature	T _s	-40		85	°C
Operating Case temperature	T _c	0		70	°C
Humidity	Rh	5		85	%
Data Rate			800		Gbps

Physical Characteristics

Parameter	Symbol	Min	Typical	Max	Unit
Length	L	0.5		5	M
AWG		32		25	AWG
Jacket material		HAIRTAIL+ Technology Net, Red			

Electrical Specifications

Parameter	Symbol	Min	Typical	Max	Unit
Power supply voltage	V _{CC}	3.1	3.3	3.5	V
Input Amplitude		800		1200	mV _{pp}
Input LOW Voltage	V _{IL}	-0.3		0.35*V _{CC}	V
Input HIGH Voltage	V _{IH}	0.65* V _{CC}		V _{CC} +0.3	V
Output Logic LOW	V _{OL}			0.25* V _{CC}	V
I2C Master Mode Output Frequency			400		kHz
800G end Power consumption			1.2	1.5	W
400G end Power consumption			0.6	0.7	W

High-Speed Specifications

Parameter	Symbol	Min	Typical	Max	Unit
Raw cable impedance	Zca	90	100	110	ohm
Mated connector Impedance	Zmated	85		115	ohm
Maximum insertion loss at 26.56 GHz	SDD21	11		19.75	dB
Differential to common-mode return loss	SCD11/22	$RL_{cd}(f) \geq \begin{cases} 22 - 10(f/26.56) & 0.05 \leq f < 26.56 \\ 15 - 3(f/26.56) & 26.56 \leq f \leq 40 \end{cases}$ For 0.05 ≤ f ≤ 40 GHz, Where f is the frequency in GHz			dB
Differential to common-mode conversion loss	SCD21-SDD21	$Conversion_loss(f) - IL(f) \geq \begin{cases} 10 & 0.05 \leq f < 12.89 \\ 14 - 0.3108f & 12.89 \leq f \leq 40 \end{cases}$ For 0.05 ≤ f ≤ 40 GHz, Where f is the frequency in GHz			dB
Common-mode to common-mode return loss	SCC11/22	$RL_{cc}(f) \geq 1.8$ For 0.05 ≤ f ≤ 40 GHz, Where f is the frequency in GHz			dB
Minimum COM	COM	3			dB
Minimum cable assembly ERL	ERL	8.25			dB
BER				2.4x10 ⁻⁴	

OSFP Pin Description

Top Side (viewed from top)

60	GND	
59	TX1p	
58	TX1n	
57	GND	
56	TX3p	
55	TX3n	
54	GND	
53	TX5p	
52	TX5n	
51	GND	
50	TX7p	
49	TX7n	
48	GND	
47	SDA	
46	VCC	
45	VCC	
44	INT/RSTn	
43	GND	
42	RX8n	
41	RX8p	
40	GND	
39	RX6n	
38	RX6p	
37	GND	
36	RX4n	
35	RX4p	
34	GND	
33	RX2n	
32	RX2p	
31	GND	

-----Module Card Edge-----

Bottom Side (viewed from bottom)

	GND	1
	TX2p	2
	TX2n	3
	GND	4
	TX4p	5
	TX4n	6
	GND	7
	TX6p	8
	TX6n	9
	GND	10
	TX8p	11
	TX8n	12
	GND	13
	SCL	14
	VCC	15
	VCC	16
	LPWn/PRSn	17
	GND	18
	RX7n	19
	RX7p	20
	GND	21
	RX5n	22
	RX5p	23
	GND	24
	RX3n	25
	RX3p	26
	GND	27
	RX1n	28
	RX1p	29
	GND	30

Electrical Pin-out Details for OSFP

Pin#	Symbol	Description	Logic	Direction	Plug Sequence	Notes
1	GND	Ground			1	
2	TX2p	Transmitter Data Non-Inverted	CML-I	Input from Host	3	
3	TX2n	Transmitter Data Inverted	CML-I	Input from Host	3	
4	GND	Ground			1	
5	TX4p	Transmitter Data Non-Inverted	CML-I	Input from Host	3	
6	TX4n	Transmitter Data Inverted	CML-I	Input from Host	3	
7	GND	Ground			1	
8	TX6p	Transmitter Data Non-Inverted	CML-I	Input from Host	3	
9	TX6n	Transmitter Data Inverted	CML-I	Input from Host	3	
10	GND	Ground			1	
11	TX8p	Transmitter Data Non-Inverted	CML-I	Input from Host	3	
12	TX8n	Transmitter Data Inverted	CML-I	Input from Host	3	
13	GND	Ground			1	
14	SCL	2-wire Serial interface clock	LVC MOS-I/O	Bi-directional	3	Open-Drain with pull-up resistor on Host
15	VCC	+3.3V Power		Power from Host	2	
16	VCC	+3.3V Power		Power from Host	2	
17	LPWn/PRSn	Low-Power Mode / Module Present	Multi-Level	Bi-directional	3	See pin description for required circuit
18	GND	Ground			1	
19	RX7n	Receiver Data Inverted	CML-O	Output to Host	3	
20	RX7p	Receiver Data Non-Inverted	CML-O	Output to Host	3	
21	GND	Ground			1	
22	RX5n	Receiver Data Inverted	CML-O	Output to Host	3	
23	RX5p	Receiver Data Non-Inverted	CML-O	Output to Host	3	
24	GND	Ground			1	
25	RX3n	Receiver Data Inverted	CML-O	Output to Host	3	
26	RX3p	Receiver Data Non-Inverted	CML-O	Output to Host	3	
27	GND	Ground			1	
28	RX1n	Receiver Data Inverted	CML-O	Output to Host	3	
29	RX1p	Receiver Data Non-Inverted	CML-O	Output to Host	3	
30	GND	Ground			1	

A-100N-O-2Q-XXXB Series Active Direct Attached Cable

Pin#	Symbol	Description	Logic	Direction	Plug Sequence	Notes
31	GND	Ground			1	
32	RX2p	Receiver Data Non-Inverted	CML-O	Output to Host	3	
33	RX2n	Receiver Data Inverted	CML-O	Output to Host	3	
34	GND	Ground			1	
35	RX4p	Receiver Data Non-Inverted	CML-O	Output to Host	3	
36	RX4n	Receiver Data Inverted	CML-O	Output to Host	3	
37	GND	Ground			1	
38	RX6p	Receiver Data Non-Inverted	CML-O	Output to Host	3	
39	RX6n	Receiver Data Inverted	CML-O	Output to Host	3	
40	GND	Ground			1	
41	RX8p	Receiver Data Non-Inverted	CML-O	Output to Host	3	
42	RX8n	Receiver Data Inverted	CML-O	Output to Host	3	
43	GND	Ground			1	
44	INT/RSTn	Module Interrupt / Module Reset	Multi-Level	Bi-directional	3	See pin description for required circuit
45	VCC	+3.3V Power		Power from Host	2	
46	VCC	+3.3V Power		Power from Host	2	
47	SDA	2-wire Serial interface data	LVC MOS-I/O	Bi-directional	3	Open-Drain with pull-up resistor on Host
48	GND	Ground			1	
49	TX7n	Transmitter Data Inverted	CML-I	Input from Host	3	
50	TX7p	Transmitter Data Non-Inverted	CML-I	Input from Host	3	
51	GND	Ground			1	
52	TX5n	Transmitter Data Inverted	CML-I	Input from Host	3	
53	TX5p	Transmitter Data Non-Inverted	CML-I	Input from Host	3	
54	GND	Ground			1	
55	TX3n	Transmitter Data Inverted	CML-I	Input from Host	3	
56	TX3p	Transmitter Data Non-Inverted	CML-I	Input from Host	3	
57	GND	Ground			1	
58	TX1n	Transmitter Data Inverted	CML-I	Input from Host	3	
59	TX1p	Transmitter Data Non-Inverted	CML-I	Input from Host	3	
60	GND	Ground			1	

Electrical Pin-out Details for QSFP

Table 15- QSFP112 Pad Function Definition

Pad	Logic	Symbol	Description	Plug Sequence ⁴	Notes
1		GND	Ground	1	1
2	CML-I	Tx2n	Transmitter Inverted Data Input	3	
3	CML-I	Tx2p	Transmitter Non-Inverted Data Input	3	
4		GND	Ground	1	1
5	CML-I	Tx4n	Transmitter Inverted Data Input	3	
6	CML-I	Tx4p	Transmitter Non-Inverted Data Input	3	
7		GND	Ground	1	1
8	LVTTL-I	ModSelL	Module Select	3	
9	LVTTL-I	ResetL	Module Reset	3	
10		VccRx	+3.3V Power Supply Receiver	2	2
11	LVC MOS-I/O	SCL	I ² C serial interface clock	3	
12	LVC MOS-I/O	SDA	I ² C serial interface data	3	
13		GND	Ground	1	1
14	CML-O	Rx3p	Receiver Non-Inverted Data Output	3	
15	CML-O	Rx3n	Receiver Inverted Data Output	3	
16		GND	Ground	1	1
17	CML-O	Rx1p	Receiver Non-Inverted Data Output	3	
18	CML-O	Rx1n	Receiver Inverted Data Output	3	
19		GND	Ground	1	1
20		GND	Ground	1	1
21	CML-O	Rx2n	Receiver Inverted Data Output	3	
22	CML-O	Rx2p	Receiver Non-Inverted Data Output	3	
23		GND	Ground	1	1
24	CML-O	Rx4n	Receiver Inverted Data Output	3	
25	CML-O	Rx4p	Receiver Non-Inverted Data Output	3	
26		GND	Ground	1	1
27	LVTTL-O	ModPrsL	Module Present	3	
28	LVTTL-O	IntL/ RxLOS	Interrupt/optional RxLOS	3	
29		VccTx	+3.3V Power supply transmitter	2	2
30		Vcc1	+3.3V Power supply	2	2
31	LVTTL-I	LPMode/ TxDis	Low Power mode/optional TX Disable	3	
32		GND	Ground	1	1
33	CML-I	Tx3p	Transmitter Non-Inverted Data Input	3	
34	CML-I	Tx3n	Transmitter Inverted Data Input	3	
35		GND	Ground	1	1
36	CML-I	Tx1p	Transmitter Non-Inverted Data Input	3	
37	CML-I	Tx1n	Transmitter Inverted Data Input	3	
38		GND	Ground	1	1

Note 1: QSFP112 uses common ground (GND) for all signals and supply (power). All are common within the QSFP-DD module and all module voltages are referenced to this potential unless otherwise noted. Connect these directly to the host board signal-common ground plane. Each connector Gnd contact is rated for a maximum current of 500 mA.

Note 2: VccRx, Vcc1, and VccTx shall be applied concurrently. Supply requirements defined for the host side of the Host Card Edge Connector are listed in Table 13. For power classes 4 and above the module differential loading of input voltage pads must not result in exceeding contact current limits. Each connector Vcc contact is rated for a maximum current of 1500 mA.

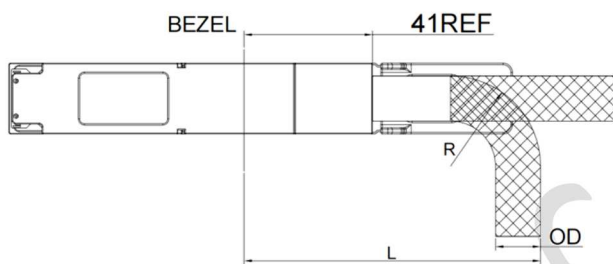
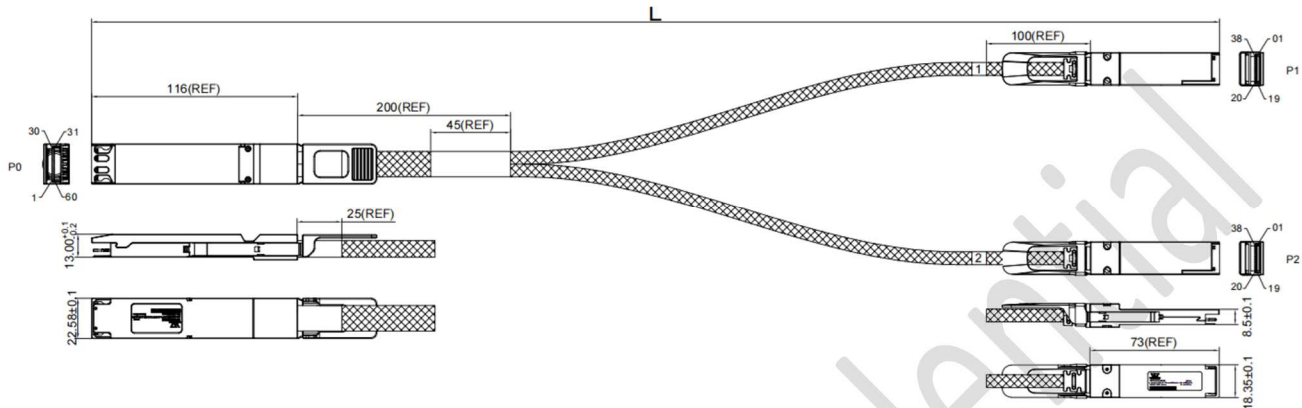
Note 4: Plug Sequence specifies the mating sequence of the host connector and module. The sequence is 1, 2, and 3 see Figure 14 for pad locations.

Module Memory Map

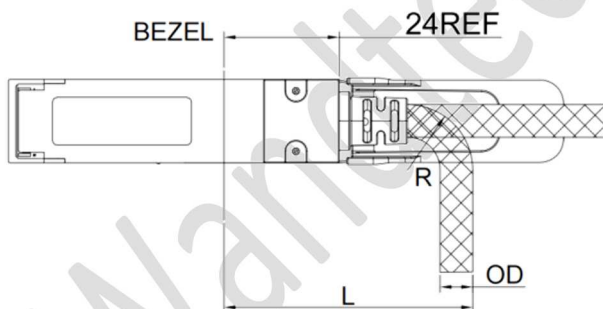
OSFP end will be compatible with CMIS rev 5.0 or further CMIS revisions and customer spec.

QSFP112 end will be compatible with SFF-8636 and customer spec.

Mechanical Dimensions



OSFP TYPE2			
GAUGE	OD	BEND RADIUS "R"	MIN. BEND RADIUS "L"
28AWG	10.2MM	21MM	65MM
26/25AWG	12.1MM	25MM	70MM



QSFP			
GAUGE	OD	BEND RADIUS "R"	MIN. BEND RADIUS "L"
28AWG	7.0MM	14MM	50MM
26/25AWG	8.3MM	17MM	55MM

Ordering Information

Model Number	Part Number	Description
A-100N-O-2Q-040B	1190200014038	800G OSFP to 2XQSFP112 ADAC,IB NDR,HAIRTAIL+, 4.0M,25AWG, RED
A-100N-O-2Q-050B	1190200014040	800G OSFP to 2XQSFP112 ADAC,IB NDR,HAIRTAIL+, 5.0M,25AWG, RED

References

1. IEEE802.3ck
2. OSFP MSA Rev5.0
3. QSFP112 MSA
4. SFF-8636
5. Common Management Interface Specification (CMIS) Rev5.0
6. IB NDR

Revision Records

REV.	Description	Designed	Checked	Approved	Issue Date
X1	Initial Released	SHAN CHEN	XICHUN TAN	RYAN LEI	2023.10.17